

# One-Step No-Clean Desoldering Braid

SKU: 301-8 | Sizes: Type A 0.635mm x 25ft, Type B 1.27mm x 10ft, Type B 1.27mm x 25ft, Type C 1.9mm x 10ft, Type C 1.9mm x 25ft, Type C 1.9mm x 100ft, Type D 2.54mm x 25ft, Type D 2.54mm x 100ft, Type E 3.175mm x 10ft, Type E 3.175mm x 25ft, Type E 3.175mm x 100ft



## Features & Benefits

- ◆ **RoHS Compliant:** Meets environmental standards for lead-free processes.
- ◆ **More Copper Strands:** Increased surface area per square inch for superior solder absorption.
- ◆ **No-Clean Flux Residue:** Flux residue left on the board does not need to be cleaned, reducing post-soldering work.
- ◆ **High SIR:** Conforms to Bellcore specification GR-78-CORE and IPC Test Method III for high Surface Insulation Resistance.
- ◆ **Compatible with RMA Fluxes:** Specifically designed for use with RMA-type no-clean fluxes.
- ◆ **Oxide-Free Clean Copper:** Ensures a clean, oxidation-free surface for efficient desoldering.
- ◆ **Eco-Friendly Manufacturing:** Manufactured using the latest environmentally-friendly chemicals and processes.

## About the One-Step No-Clean Desoldering Braid

The One-Step No-Clean Desoldering Braid is designed for efficient and clean solder removal, perfect for use in RMA-type no-clean flux processes.

This high-quality braid is RoHS compliant and conforms to ANSI/J-STD-004, Type LO, as well as IPC Test Method III, ensuring it meets the highest industry standards. The braid is made with oxide-free, clean copper, offering more copper strands per square inch for greater surface area and faster, more effective solder absorption. The flux residue left on the board after use doesn't require cleaning, making it ideal for time-efficient and clean desoldering.

## Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms